SMART DESOLDER 01





DS01.1001 SMART DESOLDER 01

The SMART DESOLDER combines a manual hot gas source with a vacuum pen for extraction of residual solder. Damage to the pads from overheating or mechanical stress is avoided through targeted heating of the residual solder after lifting the component. The temperature-controlled airflow prevents the neighboring components from warming up.

After melting, the residual solder is removed contactless by the vacuum pen. The use of a Teflon tip in the vacuum pen offers outstanding features: the nonstick effect, the temperature-resistance and the mechanically soft surface of the material.

As a stand-alone device, it virtually fits on any work bench and can be operated very flexible with two handheld pens.

Standard Equipment

- Two handheld pens with magazine for soldering and residual solder removal
- Solder nozzle 4mm
- Solder sucker nozzle complete with Teflon tip 1.4mm
- Cleaner solder sucker nozzle
- Flux filter and solder separator for old solder

Technical dataPower consumption:480 WPower solder pen:380 W, 25 l/minMains:100 – 240VAC, fuse TG,3APressurized air:7.5 l/min max. 4bar
clean, dry airFootprint:270 x 150 x 60 mm²

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Optional Extras

HF00.0004	Handy Fix 03.1 Base plate 280*380mm, 4x magnet holder, h=40.5mm	
HF00.0016	Handy Fix 06 Base plate 280*380mm 4x magnet holder h=55.5=>69,5mm adjustable	S S S
SF03.0019	PCB clamping holder with 3 fingers for mobile phone pcbs on HB05/IRx/HIF h=40.5mm	40.5

Accessories

DV15.0030 Flux filter for cooler of solder sucker nozzle	
HT00.0019 Clean Pen for pads and IR glass with 3 spare erasers	
HT00.0119 Flux Creme lead free 18g 0506 MA, no clean, REL0, with brush	> Lead free
DV15.0016 Solder sucker nozzle 0.5mm for μSMD/CSP/QFP, only teflon tip	
DV15.0015 Solder sucker nozzle 1.0mm for μSMD/CSP/QFP, only teflon tip	
DB50.0004 Soldering nozzle 7mm	
DB50.0002 Soldering nozzle 3mm	
DB50.0001 Soldering nozzle 2 mm	

Further units and consumables under <u>www.martin-smt.de</u>